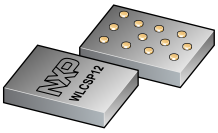
SOT2240-1

BARE DIE-12 I/O (WITH GOLD BUMP) 0.984 X 0.74 X 0.168 PKG, PITCH

21 May 2024 **Package information**



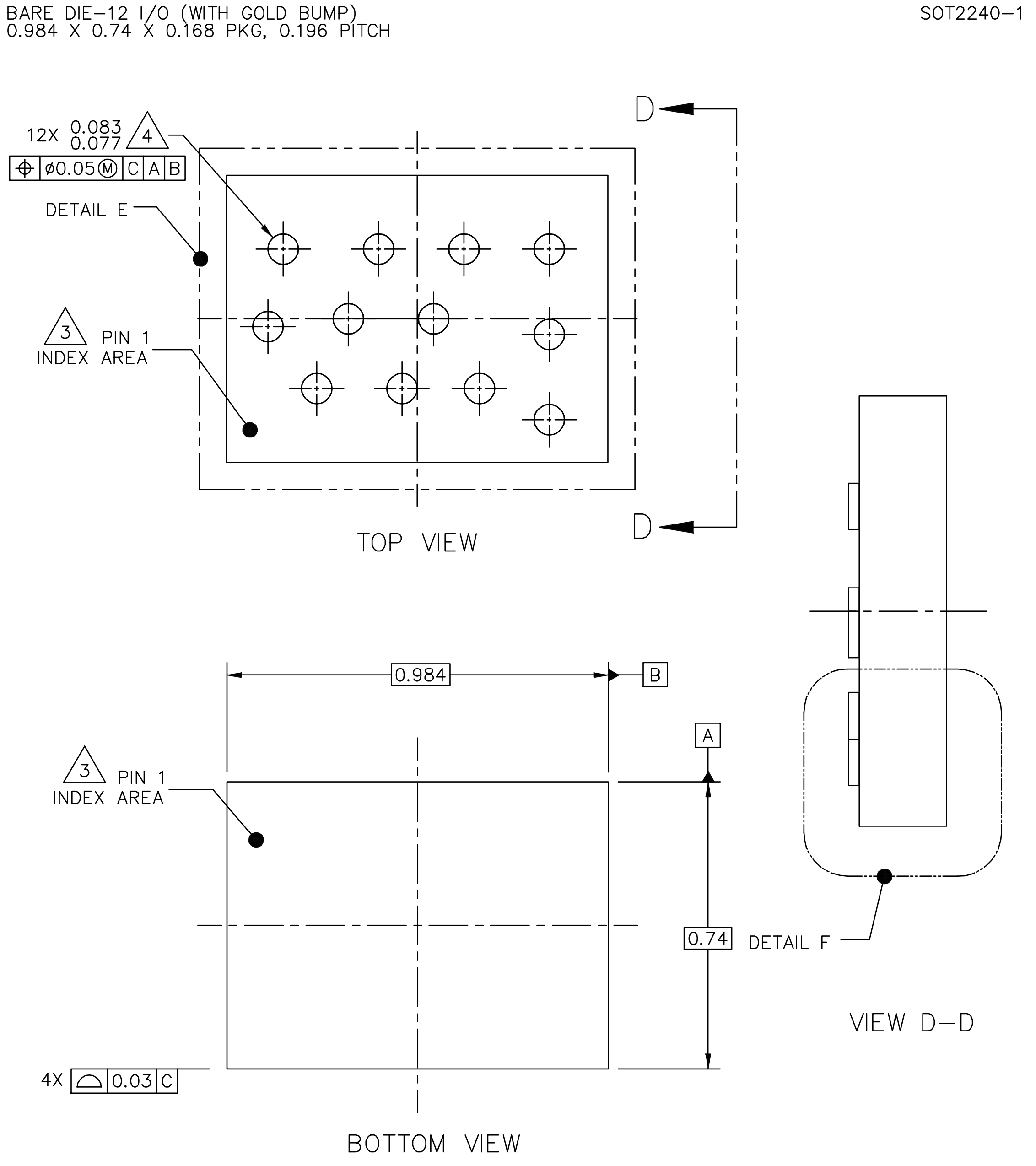
1 Package summary

Terminal position code	S (single)
Package type descriptive code	FC Die 12
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	S (silicon)
Mounting method type	P (post (stud) mount)
Issue date	14-05-2024
Manufacturer package code	98ASA02156D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.954	0.984	1.014	mm
package width	0.71	0.74	0.77	mm
package height	0.147	0.165	0.183	mm
nominal pitch	-	0.196	-	mm
actual quantity of termination	-	12	-	

2 Package outline



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DATE: 29 MAR 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02156D	REVISION: O	

Figure 1. Package outline WLCSP12 (SOT2240-1)

BARE DIE−12 I/O (WITH GOLD BUMP)
0.984 X 0.74 X 0.168 PKG, 0.196 PITCH

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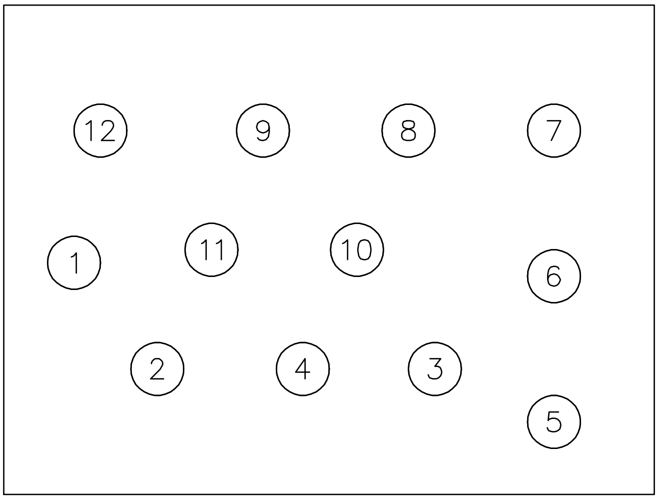
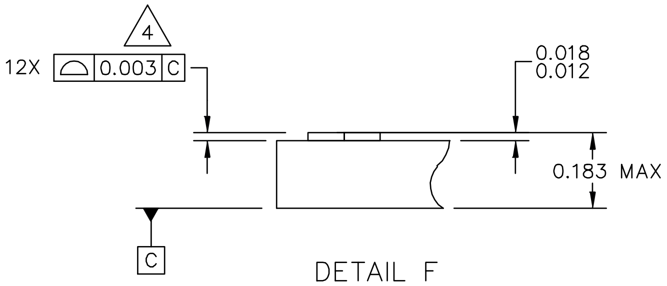


PIN NUMBERS
(VIEW ON DETAIL E)



SEATING PLANE

DETAIL F
VIEW ROTATED 90° CW

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Figure 2. Package outline detail E and F of WLCSP12 (SOT2240-1)

3 Soldering

BARE DIE–12 I/O (WITH GOLD BUMP)
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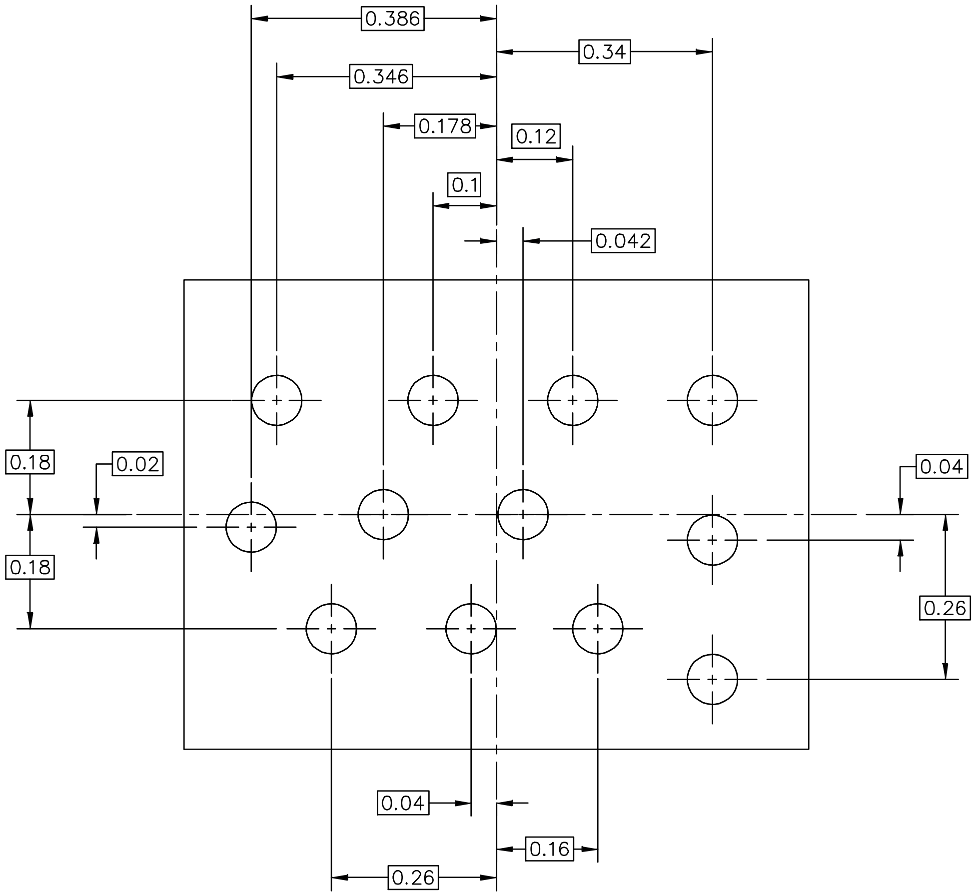

DATE: 29 MAR 2024

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA02156D	REVISION: 0	

Figure 3. Reflow soldering footprint part1 for WLCSP12 (SOT2240-1)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

△3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

△4. DIMENSIONS APPLY TO ALL PINS.

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Figure 4. Package outline note WLCSP12 (SOT2240-1)

4 Legal information

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